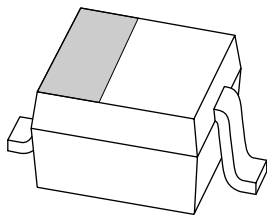


# DATA SHEET



## **BAP65-03** Silicon PIN diode

Product specification  
Supersedes data of 2001 May 11

2004 Feb 11

# Silicon PIN diode

# BAP65-03

## FEATURES

- High voltage, current controlled
- RF resistor for RF switches
- Low diode capacitance
- Low diode forward resistance (low loss)
- Very low series inductance.

## APPLICATIONS

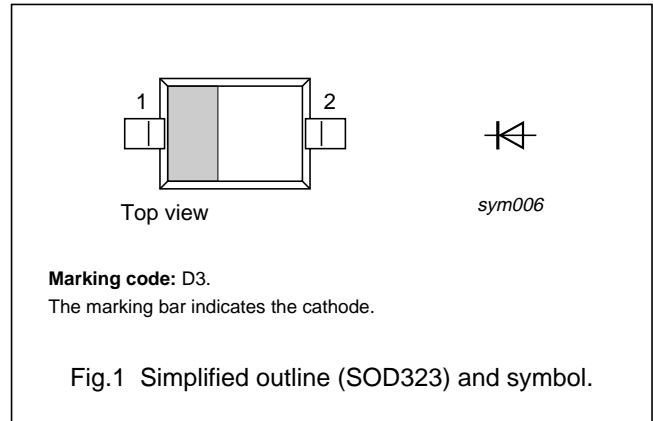
- RF attenuators and switches
- Bandswitch for TV tuners
- Series diode for mobile communication transmit/receive switch.

## DESCRIPTION

Planar PIN diode in a SOD323 small SMD plastic package.

## PINNING

PIN	DESCRIPTION
1	cathode
2	anode



## ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BAP65-03	–	plastic surface mounted package; 2 leads	SOD323

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_R$	continuous reverse voltage		–	30	V
$I_F$	continuous forward current		–	100	mA
$P_{tot}$	total power dissipation	$T_s \leq 90\text{ °C}$	–	500	mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–65	+150	°C

## Silicon PIN diode

## BAP65-03

**ELECTRICAL CHARACTERISTICS**T<sub>j</sub> = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 50 mA	0.9	1.1	V
I <sub>R</sub>	reverse leakage current	V <sub>R</sub> = 20 V	–	20	nA
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 0 V; f = 1 MHz	0.65	–	pF
		V <sub>R</sub> = 1 V; f = 1 MHz	0.55	0.9	pF
		V <sub>R</sub> = 3 V; f = 1 MHz	0.5	0.8	pF
		V <sub>R</sub> = 20 V; f = 1 MHz	0.375	–	pF
r <sub>D</sub>	diode forward resistance	I <sub>F</sub> = 1 mA; f = 100 MHz	1	–	Ω
		I <sub>F</sub> = 5 mA; f = 100 MHz; note 1	0.65	0.95	Ω
		I <sub>F</sub> = 10 mA; f = 100 MHz; note 1	0.56	0.9	Ω
		I <sub>F</sub> = 100 mA; f = 100 MHz	0.35	–	Ω
S <sub>21</sub>   <sup>2</sup>	isolation	V <sub>R</sub> = 0; f = 900 MHz	10.2	–	dB
		V <sub>R</sub> = 0; f = 1800 MHz	5.8	–	dB
		V <sub>R</sub> = 0; f = 2450 MHz	4.1	–	dB
S <sub>21</sub>   <sup>2</sup>	insertion loss	I <sub>F</sub> = 1 mA; f = 900 MHz	0.1	–	dB
		I <sub>F</sub> = 1 mA; f = 1800 MHz	0.14	–	dB
		I <sub>F</sub> = 1 mA; f = 2450 MHz	0.18	–	dB
S <sub>21</sub>   <sup>2</sup>	insertion loss	I <sub>F</sub> = 5 mA; f = 900 MHz	0.06	–	dB
		I <sub>F</sub> = 5 mA; f = 1800 MHz	0.1	–	dB
		I <sub>F</sub> = 5 mA; f = 2450 MHz	0.14	–	dB
S <sub>21</sub>   <sup>2</sup>	insertion loss	I <sub>F</sub> = 10 mA; f = 900 MHz	0.06	–	dB
		I <sub>F</sub> = 10 mA; f = 1800 MHz	0.1	–	dB
		I <sub>F</sub> = 10 mA; f = 2450 MHz	0.13	–	dB
S <sub>21</sub>   <sup>2</sup>	insertion loss	I <sub>F</sub> = 100 mA; f = 900 MHz	0.05	–	dB
		I <sub>F</sub> = 100 mA; f = 1800 MHz	0.1	–	dB
		I <sub>F</sub> = 100 mA; f = 2450 MHz	0.14	–	dB
τ <sub>L</sub>	charge carrier life time	when switched from I <sub>F</sub> = 10 mA to I <sub>R</sub> = 6 mA; R <sub>L</sub> = 100 Ω; measured at I <sub>R</sub> = 3 mA	0.17	–	μs
L <sub>S</sub>	series inductance	I <sub>F</sub> = 100 mA; f = 100 MHz	1.5	–	nH

**Note**

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

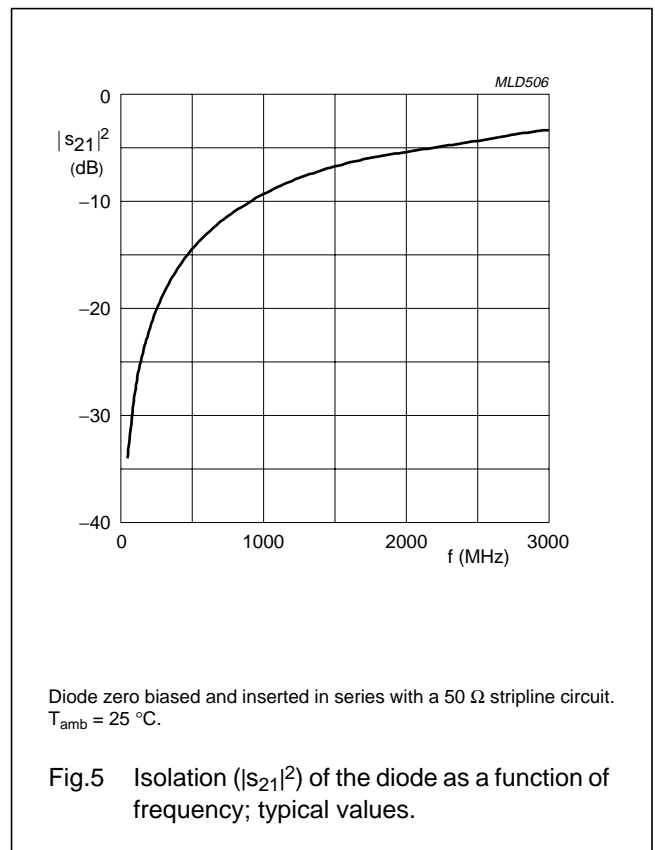
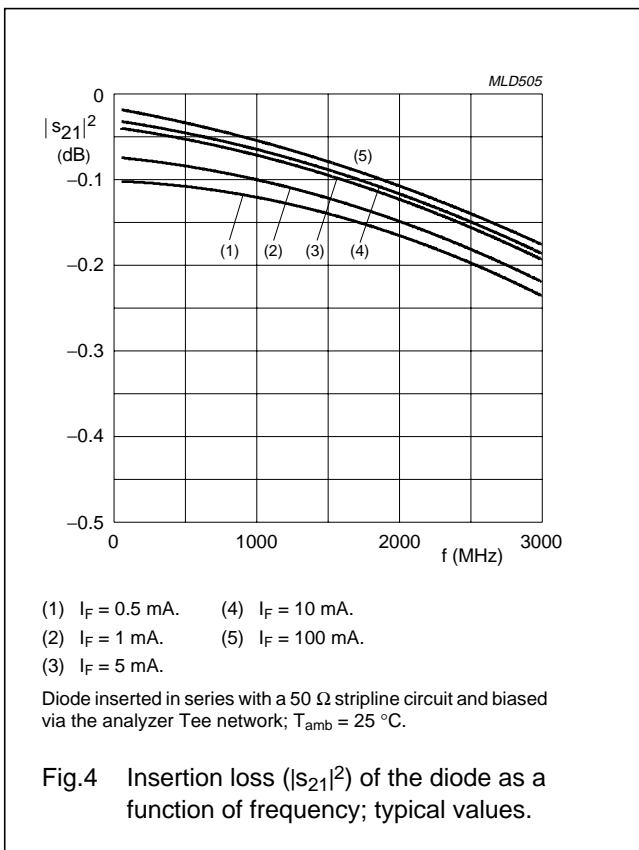
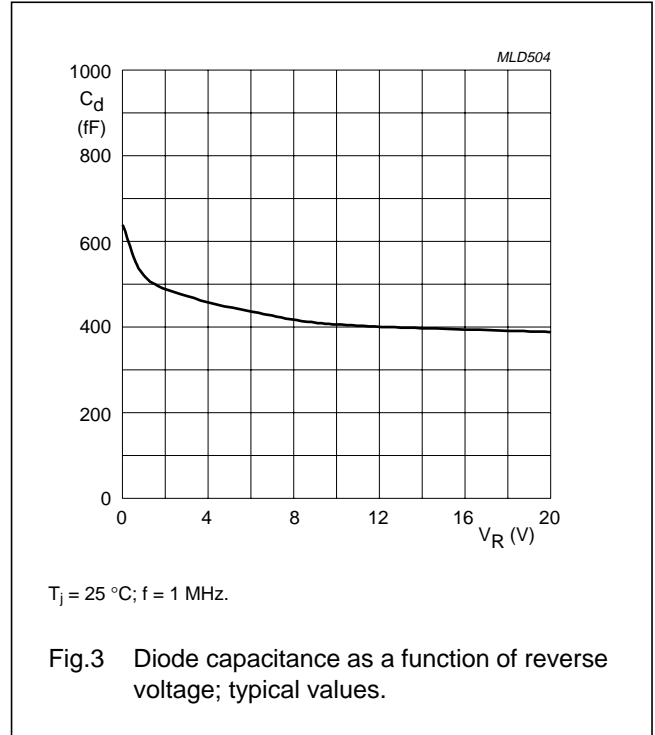
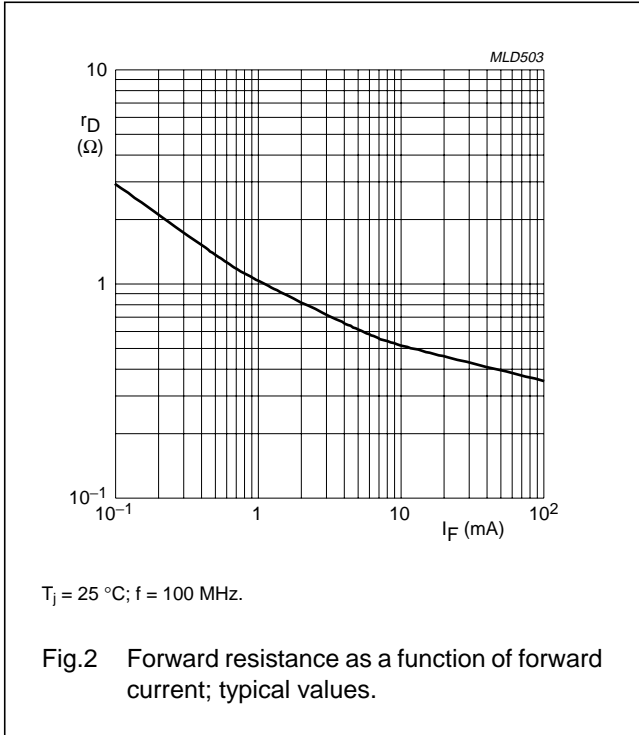
**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th(j-s)</sub>	thermal resistance from junction to soldering point	120	K/W

Silicon PIN diode

BAP65-03

GRAPHICAL DATA



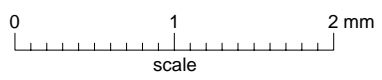
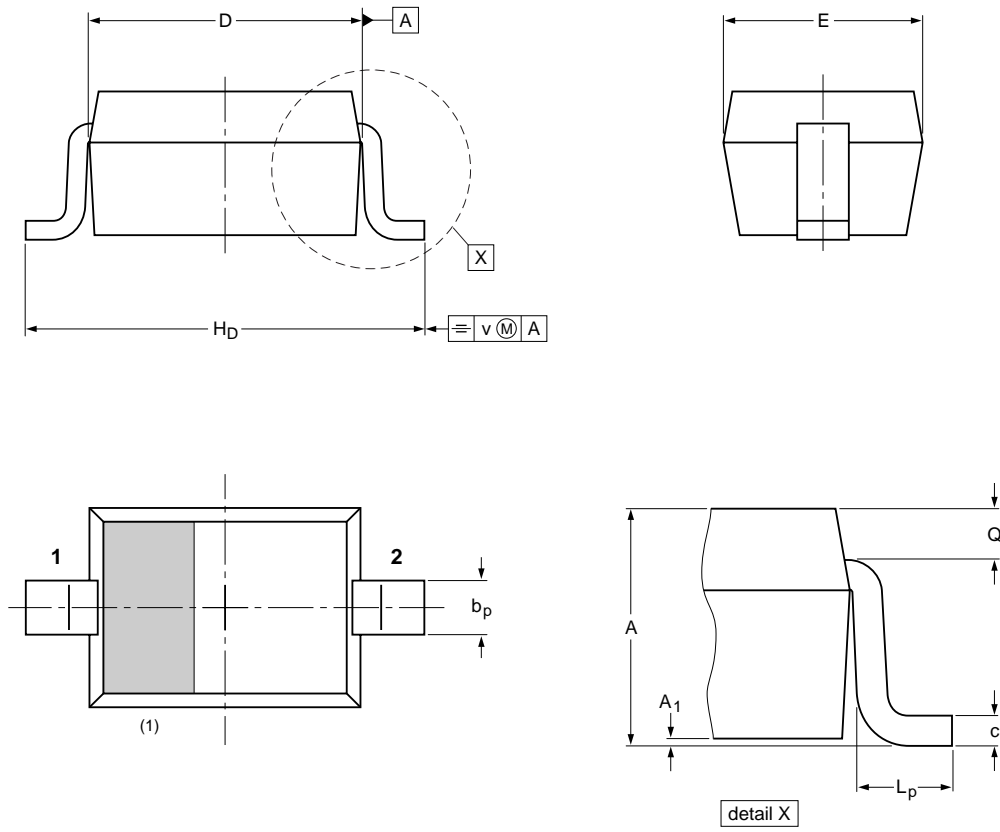
Silicon PIN diode

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PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	H <sub>D</sub>	L <sub>p</sub>	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOD323			SC-76		99-09-13 03-12-17

## Silicon PIN diode

BAP65-03

## DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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